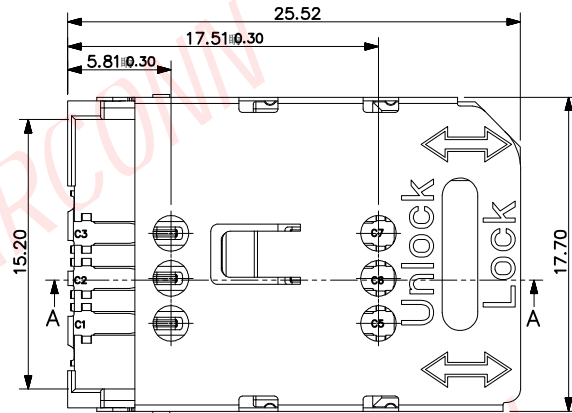
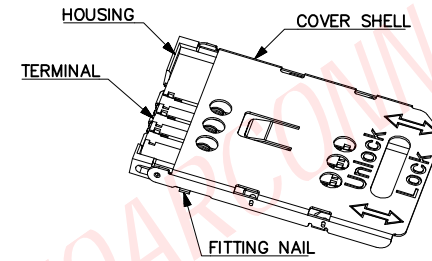
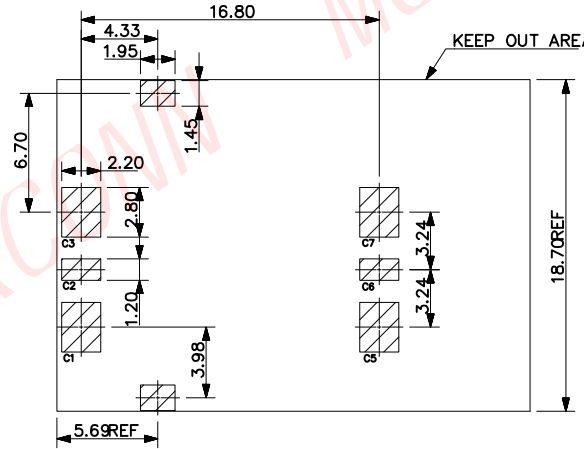
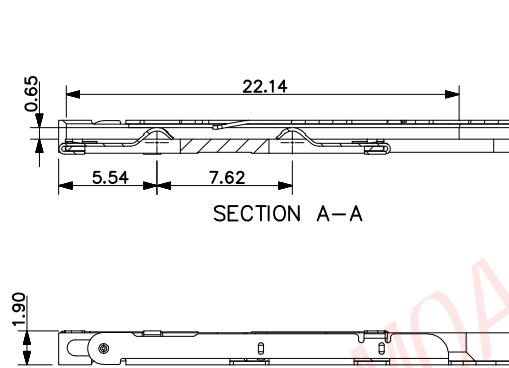
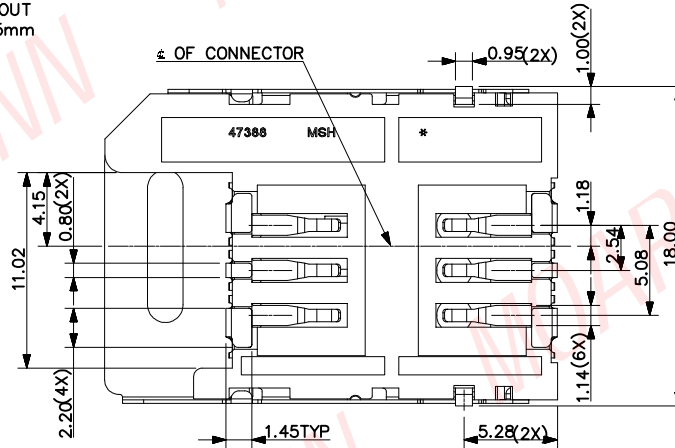
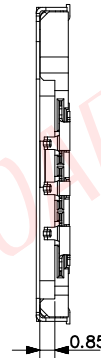


All materials, plating and process meet HF requirements.



RECOMMENDED PCB LAYOUT
TOLERANCE: 0.05mm



NOTES:

1.MATERIALS:

HOUSING: LCP, GLASS FILLED, UL 94V-0, COLOR: BLACK.
TERMINAL: PHOSPHOR BRONZE, THICKNESS: 0.15mm.
COVER SHELL: STAINLESS STEEL, THICKNESS: 0.20mm.
FITTING NAIL: BRASS, THICKNESS: 0.20mm.

2.FINISH:

TERMINAL:
CONTACT AREA: 0.75MICRON MIN GOLD PLATE OVER 1.27MICRON MIN NICKEL.
SOLDER AREA: 3.8MICRON MIN TIN PLATE OVER 1.27MICRON MIN NICKEL.
FITTING NAIL: 2.54MICRON MIN TIN OVER 1.27MICRON MIN NICKEL OVERALL.

3.COPLANARITY: 0.10mm MAX AMONG ALL SOLDER TAILS.

4.PRODUCT SPECIFICATION: PS-47388-201.

5.PACKAGING SPECIFICATION: PK-47388-001.

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DIMENSIONS INIT: mm UNLESS OTHERWISE SPECIFIABLE DIMENSION TOLERANCE X.X: ± 0.10 X.XX: ± 0.05 X.XXX: ± 0.02 ANGULAR: ± 1°	PRODUCT NAME :	SIM card H1.90 SMT	DRAWING:	Zhangli	DATE:	2025.1.4	
	PRODUCT NO. :	SM190-T6250-01-W	CHECK:	/	DATE:	/	
	DRAWING NO. :	D-SM190-T6250-01-W	APPROVED:		DATE:		
	SCALE:	1:1	DWG ID:	P D	REV.:	X0	PAGE:

X0	-----	NEW RELEASE	Aaron	2024.11.09
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
1		2	3	4